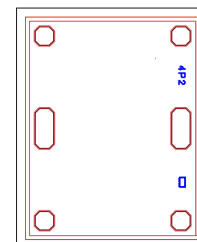


MMIC

# Power Splitter/Combiner Die

WP4P1-D+

4 Way-0° 50Ω 1525 to 2375 MHz



## The Big Deal

- Wide Bandwidth, 1525 to 2375 MHz
- Excellent Amplitude Unbalance, 0.15 dB typ.

## Product Overview

Mini-Circuits' WP4P1-D+ is a MMIC 4-way 0° splitter/combiner Die designed for wideband operation from 1525 to 2375 MHz. Manufactured using Si IPD technology, its compact size saves valuable space in hybrids.

## Key Features

Feature	Advantages
Bandwidth, 1525 to 2375 MHz	One power splitter can be used in many applications, saving component count.
Excellent Amplitude Unbalance, 0.15 dB typ. and Good Phase Unbalance, 1 deg. typ.	Excellent Amplitude and phase unbalance helps to accurately divide the input signals which is essential in test and measurement circuits.
Unpackaged Die, 0.855 x 1.069 mm	Enables user to integrate it directly into hybrids. Small die size saves space in customer hybrids.



# MMIC Power Splitter/Combiner Die

## WP4P1-D+

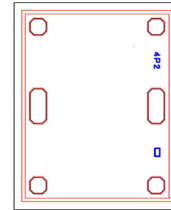
4 Way-0° 50Ω 1525 to 2375 MHz

### Product Features

- Wide bandwidth, 1525 to 2375 MHz
- Excellent amplitude unbalance, 0.15 dB typ.

### Applications

- PCS/DCS
- WCDMA
- GPS



**+RoHS Compliant**

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

**Ordering Information: Refer to Last Page**

### General Description

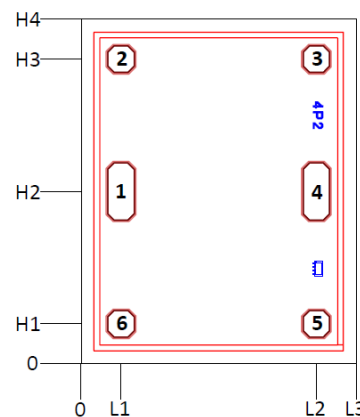
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### Simplified Schematic and Pad Description



Pad#	Function
1	RF IN
2	RF OUT 1
3	RF OUT 2
5	RF OUT 3
6	RF OUT 4
4	Ground

### Bonding Pad Position



Dimensions in  $\mu\text{m}$ , Typical

L1	L2	L3	H1	H2	H3	H4	Thickness	Die Size	Pad Size 1 & 4	Pad Size 2,3,5 & 6
124	731	855	124	534	945	1069	254	855x1069	82 x 177	82 x 82



**Electrical Specifications at 25°C<sup>1</sup>**

Parameter	Frequency (MHz)	Min.	Typ.	Max.	Unit
Frequency Range		1525		2375	MHz
Insertion Loss above 3.0 dB	1525 - 2375		0.9		dB
Isolation	1525 - 2375		26		dB
Phase Unbalance	1525 - 2375		2.0		Degree
Amplitude Unbalance	1525 - 2375		0.2		dB
VSWR (Port S)	1525 - 2375		1.5		:1
VSWR (Port 1,2,3,4)	1525 - 2375		1.4		:1

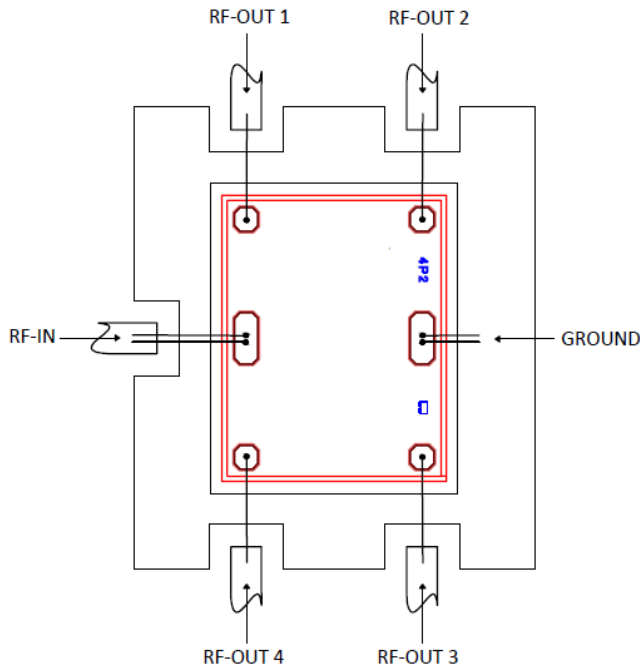
1. Tested in 3x3mm, Mini-Circuits 12-lead MCLP package.

**Maximum Ratings<sup>1,2</sup>**

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Power Input (as a splitter)	1.5W
Internal Dissipation	0.375W

2. Permanent damage may occur if any of these limits are exceeded.

## Assembly Diagram



## Assembly and Handling Procedure

1. Storage  
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD  
MMIC dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach  
The Die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total Die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic Die pick up tools only.
4. Wire Bonding  
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the Die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

<b>Additional Detailed Technical Information</b> <i>additional information is available on our dash board.</i>							
<b>Performance Data</b>	Data Table						
	Swept Graphs						
	S-Parameter (S5P Files) Data Set with and without port extension(.zip file)						
<b>Case Style</b>	Die						
<b>Die Ordering and packaging information (Note 5)</b>	<table> <tr> <td>Quantity, Package</td> <td>Model No.</td> </tr> <tr> <td>Small, Gel - Pak: 5,10,50,100 KGD*</td> <td>WP4P1-DG+</td> </tr> <tr> <td>Medium†, Partial wafer: KGD*&lt;1554</td> <td>WP4P1-DP+</td> </tr> </table> <p>†Available upon request contact sales representative</p> <p>Refer to <a href="#">AN-60-067</a></p>	Quantity, Package	Model No.	Small, Gel - Pak: 5,10,50,100 KGD*	WP4P1-DG+	Medium†, Partial wafer: KGD*<1554	WP4P1-DP+
Quantity, Package	Model No.						
Small, Gel - Pak: 5,10,50,100 KGD*	WP4P1-DG+						
Medium†, Partial wafer: KGD*<1554	WP4P1-DP+						
<b>Environmental Ratings</b>	ENV-80						

\*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected in question have been subjected to Mini-Circuits while this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

## ESD Rating\*\*

Human Body Model (HBM): Class 1A (Pass 250V) in accordance with ANSI/ESD STM 5.1 - 2001

\*\* Tested in 3x3mm, Mini-Circuits 12-lead MCLP package.

### Additional Notes

- Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
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